

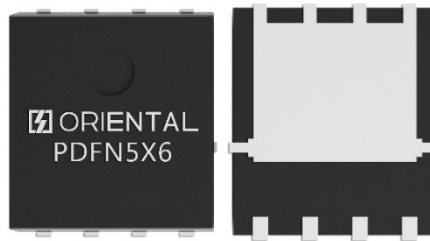
PDFN5X6 Package Type

1、封装尺寸:

封装尺寸为 5mm×6mm，厚度约 0.95mm，属于紧凑型封装，适合对空间要求较高的应用场景，如汽车电子、消费电子等。

1. Package Dimensions

The package measures 5mm×6mm with a thickness of approximately 0.95mm. Classified as a compact package, it is well-suited for space-constrained applications such as automotive electronics and consumer electronics.

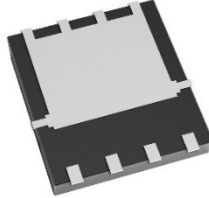


2、散热性能:

部分 PDFN5X6 封装采用双面散热设计，通过顶部和底部的散热金属层将芯片热量直接传导至外部，有效降低热阻，提升散热效率，尤其适用于高功率密度场景。

2. Heat Dissipation Performance

Some PDFN5×6 packages adopt a double-sided cooling design. They conduct heat from the chip directly to the outside via the top and bottom heat-dissipating metal layers, effectively reducing thermal resistance and improving heat dissipation efficiency. This design is particularly suitable for high-power-density scenarios.

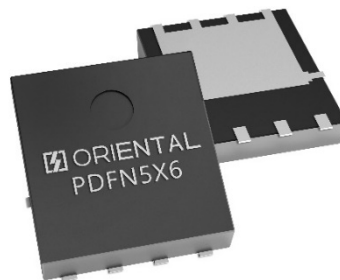


3、电气性能:

通常用于中低压功率 MOSFET 或 IGBT 等器件，具有低导通电阻 ($R_{ds(on)}$)、低栅极电荷 (Q_g)，支持高频开关，可降低导通损耗和开关损耗，提高系统能效。

3. Electrical Performance

It is typically used for medium-and low-voltage power devices such as MOSFETs and IGBTs. Featuring low on-resistance ($R_{ds(on)}$) and low gate charge (Q_g), it supports high-frequency switching, which can reduce conduction losses and switching losses while improving system energy efficiency.



4、应用领域:

常见于汽车电子（如电池管理系统、车载充电器、电机驱动）、消费电子（快充、电源管理）、工业控制等领域，适用于需要高可靠性、高功率密度的场景。

4. Application Fields

It is commonly used in fields such as automotive electronics (e.g., battery management systems,



on-board chargers, motor drives), consumer electronics (fast charging, power management), and industrial control. It is suitable for scenarios requiring high reliability and high power density.



5、工艺特点:

采用铜夹片 (Cu Clip) 或铝线键合等工艺, 结合顶部开窗设计, 优化热流路径和电气连接, 兼顾散热与信号传输性能。

5. Process Features

It adopts processes such as copper clip (Cu Clip) or aluminum wire bonding, combined with a top windowing design. This optimizes the heat flow path and electrical connection, achieving a balance between heat dissipation performance and signal transmission performance.